Revision history

<table>
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<tr>
<th>Rev</th>
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<th>Description</th>
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<tr>
<td>1.8</td>
<td>20180830</td>
<td>• Added $V_{REFP}$</td>
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<td>1.7</td>
<td>20180302</td>
<td>• Added USB ROM.2.</td>
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<tr>
<td>1.6</td>
<td>20180226</td>
<td>• Updated work-around for Section 3.4 “USB:1: Automatic USB rate adjustment is not functional when using multiple hubs”</td>
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<tr>
<td>1.5</td>
<td>20170804</td>
<td>• Added USB ROM.1.</td>
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<tr>
<td>1.4</td>
<td>20170505</td>
<td>• Updated Table 2 “Functional problems table”: changed heading row to Functional problems.</td>
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<tr>
<td>1.3</td>
<td>20170421</td>
<td>• Added CRP.1.</td>
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<td></td>
<td></td>
<td>• Removed IAP.1. IAP call is functional. Use the procedure described in the LPC5411x user manual.</td>
</tr>
<tr>
<td>1.2</td>
<td>20161014</td>
<td>• Added I²S.3.</td>
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<tr>
<td></td>
<td></td>
<td>• Added I²C.1.</td>
</tr>
<tr>
<td></td>
<td></td>
<td>• Added USART.1.</td>
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<td>1.1</td>
<td>20160222</td>
<td>• Added USB.1.</td>
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<tr>
<td></td>
<td></td>
<td>• Added I²S.1.</td>
</tr>
<tr>
<td></td>
<td></td>
<td>• Added I²S.2.</td>
</tr>
<tr>
<td></td>
<td></td>
<td>• Removed deep-sleep2 from Section 3.3 “ADC:1: High current consumption in reduced low power modes when using ADC.”</td>
</tr>
<tr>
<td>1</td>
<td>20160216</td>
<td>• Initial version</td>
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</tbody>
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Contact information

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1. Product identification

The ES_LPC5411x LQFP64 package has the following top-side marking:

- First line: LPC5411xJyyy
  - x: 4 = dual core (M4, M0+), 1, 3 = single core (M4)
  - yyy: flash size
- Second line: BD64
- Third line: xxxxxxxxxxxx
- Fourth line: xxyywwx[R]x
  - yyww: Date code with yy = year and ww = week.
- R = Chip revision.

The ES_LPC5411x WLCSP49 package has the following top-side marking:

- First line: LPC5411x
  - x: 4 = dual core (M4, M0+), 1, 3 = single core (M4)
- Second line: JxxxUK49
  - xxx: flash size
- Third line: xxxxxxxx
- Fourth line: xxyyww
  - yyww: Date code with yy = year and ww = week.
- Fifth line: xxxxx
- Sixth line: NXP x[R]x
  - R = Chip revision.

Table 1. Device revision table

<table>
<thead>
<tr>
<th>Revision identifier (R)</th>
<th>Revision description</th>
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<tbody>
<tr>
<td>'A'</td>
<td>Initial device revision</td>
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2. **Errata overview**

Table 2. **Functional problems table**

<table>
<thead>
<tr>
<th>Functional problems</th>
<th>Short description</th>
<th>Revision identifier</th>
<th>Detailed description</th>
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<tbody>
<tr>
<td>ISP.1</td>
<td>ISP (In-System Programming) command for UID (unique identification number) is not functional.</td>
<td>'A'</td>
<td>Section 3.1</td>
</tr>
<tr>
<td>ISP.2</td>
<td>ISP 'Z' command is not reliable for flash signature generation.</td>
<td>'A'</td>
<td>Section 3.2</td>
</tr>
<tr>
<td>ADC.1</td>
<td>High current consumption in reduced low power modes when using ADC.</td>
<td>'A'</td>
<td>Section 3.3</td>
</tr>
<tr>
<td>USB.1</td>
<td>Automatic USB rate adjustment not functional when using multiple hubs.</td>
<td>'A'</td>
<td>Section 3.4</td>
</tr>
<tr>
<td>I²S.1</td>
<td>FIFO underflow interrupt not generated for I²S peripheral.</td>
<td>'A'</td>
<td>Section 3.5</td>
</tr>
<tr>
<td>I²S.2</td>
<td>The Most Significant Bit (MSB) of I²S receive data is forced to 0 if DATALEN is greater than 23.</td>
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<td>Section 3.6</td>
</tr>
<tr>
<td>I²S.3</td>
<td>Incorrect synchronization to the second edge of the WS instead of the start of frame.</td>
<td>'A'</td>
<td>Section 3.7</td>
</tr>
<tr>
<td>I²C.1</td>
<td>The AUTOACK feature does not work reliably when the CPU system clock frequency is three times or more than the peripheral clock to the I²C interface.</td>
<td>'A'</td>
<td>Section 3.8</td>
</tr>
<tr>
<td>USART.1</td>
<td>The USART receiver timeout feature is not supported.</td>
<td>'A'</td>
<td>Section 3.9</td>
</tr>
<tr>
<td>USART.2</td>
<td>The USART receiver idle (RXIDLE) interrupt feature is not supported.</td>
<td>'A'</td>
<td>Section 3.10</td>
</tr>
<tr>
<td>CRP.1</td>
<td>Code read protection level 1 is not functional.</td>
<td>'A'</td>
<td>Section 3.11</td>
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<tr>
<td>USB_ROM.1</td>
<td>FRAME_INT is cleared if new SetConfiguration or USB_RESET are received.</td>
<td>'A'</td>
<td>Section 3.12</td>
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<tr>
<td>USB_ROM.2</td>
<td>USB full-speed device fail in the Command/Data/Status Flow after bus reset and bus re-enumeration.</td>
<td>'A'</td>
<td>Section 3.13</td>
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<tr>
<td>VREFP.1</td>
<td>For VREFP &lt; VDD, the deep power-down current is higher than expected.</td>
<td>'A'</td>
<td>Section 4.1</td>
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</table>

Table 3. **AC/DC deviations table**

<table>
<thead>
<tr>
<th>AC/DC deviations</th>
<th>Short description</th>
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<td>n/a</td>
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Table 4. **Errata notes**

<table>
<thead>
<tr>
<th>Note</th>
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<th>Revision identifier</th>
<th>Detailed description</th>
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<td>n/a</td>
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<td>n/a</td>
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</tbody>
</table>
3. Functional problems detail

3.1 ISP: ISP (In-System Programming) command for UID (unique identification number) is not functional.

Introduction:
Each LPC5411x device contains a device serial number (four 32-bit words) for unique identification. The ISP call (ReadUID) can be performed via the USART interface to read the unique serial number where the word at the lowest address is sent first.

Problem:
On the LPC5411x, the read UID ISP command is not functional.

Work-around:
The unique serial number (four 32-bit words) can be directly read from address locations 0x0100 0100 to 0x0100 010C.
3.2 ISP.2: ISP ‘Z’ command is not reliable for flash signature generation

Introduction:

On the LPC5411x devices, the ISP ‘Z’ command is used to determine the signature of the entire flash memory using an internal flash signature generator.

Problem:

The ISP ‘Z’ command is not reliable on the LPC5411x devices. In most cases, the signature will be correct but due to a signature generation timing sensitivity, the result may be incorrect and therefore unreliable.

Work-around:

Use the flash signature generation registers documented in the LPC5411x User Manual to create the signature of the entire flash memory.
3.3 ADC.1: High current consumption in reduced low power modes when using ADC.

**Introduction:**

The 12-bit ADC controller is available on all LPC5411x parts. The ADC can measure the voltage on any of the input signals on the analog input channel. For accurate voltage readings, the digital pin function on the ADC input channel must be disabled by writing a 0 to the DIGIMODE bit in the related IOCON register. This enables the analog mode functionality on the ADC input channel.

**Problem:**

For applications using the ADC, the current consumption could be higher than expected in reduced power modes (deep-sleep and deep power-down modes) or when the ADC is disabled using the PDRUNCFG register.

**Work-around:**

To prevent high current consumption, use the following steps in the software:

1. Following a chip reset, all 12 ADC input channels (ADC0_0 to ADC0_11) should be in Digital Mode (DIGIMODE = 1) in the related IOCON registers until the configuration of the ADC block is complete. See the Basic Configuration section in the LPC5411x 12-bit ADC controller (ADC) chapter of the LPC5411x User Manual.

2. After configuring the ADC, change only those pins that are used as ADC input channels to Analog Mode (DIGIMODE = 0) in the related IOCON registers before starting ADC conversions.

3. Before entering any reduced power mode (deep-sleep and deep power-down) or before powering down the ADC block (by writing to the PDEN_ADC0 bit in the PDRUNCFG register), the ADC input channel(s) must be changed back to Digital Mode.

4. After waking up from the reduced power mode or when re-enabling the ADC block (PDEN_ADC0 bit in the PDRUNCFG), the software must follow step 2 before starting ADC conversions.
3.4 USB.1: Automatic USB rate adjustment is not functional when using multiple hubs

Introduction:

Full-speed and low-speed signaling uses bit stuffing throughout the packet without exception. If the receiver sees seven consecutive ones anywhere in the packet, then a bit stuffing error has occurred, and the packet should be ignored.

The time interval just before an End of Packet (EOP) is a special case. The last data bit before the EOP can become stretched by hub switching skews. This is known as dribble and can lead to a situation where dribble introduces a sixth bit that does not require a bit stuff. Therefore, the receiver must accept a packet where there are up to six full bit times at the port with no transitions prior to the EOP.

Problem:

LPC5411x devices use the start of an EOP for frequency measurements. This is not functional when going through multiple hubs that introduce a dribble bit because of hub switching skews. For this reason, the start of the EOP cannot be used for frequency measurements for automatic USB rate adjustment (by setting USBCLKADJ in FROCTRL register). The problem does not occur when a single hub is used.

Work-around:

Use the FRO calibration library provided in TN00031. This library allows the application to have a crystal-less USB device operation in full-speed mode.
3.5 I2S.1: FIFO underflow interrupt not generated for I2S peripheral

Introduction:
Multiple Flexcomm Interfaces are available in the LPC5411x devices. Flexcomm Interface 6 and Flexcomm Interface 7 can be configured for I2S peripheral function and the data for all I2S traffic within one Flexcomm Interface uses the Flexcomm Interface FIFO. During I2S data transfers, when the transmit FIFO is empty, a FIFO underflow occurs and an interrupt is generated, which is flagged by the UNDERRUN bit in the I2S FIFOSTAT register.

Problem:
When the FIFO underflow condition occurs, the interrupt from the I2S peripheral function might not be generated and as a result, the UNDERRUN bit does not get set. This issue does not affect the SPI and USART peripherals.

Work-around:
There is no work-around.
3.6 I²S.1: The Most Significant Bit (MSB) of I²S receive data is forced to zero if DATALEN > 23

**Introduction:**

On the LPC5411x devices, the I²S function is included in Flexcomm Interface 6 and Flexcomm Interface 7. Each of these Flexcomm Interfaces implements one I²S channel pair. The Data Length (DATALEN) defines the number of data bits to be transmitted or received for all I²S channel pairs.

**Problem:**

If the I²S interface is configured for DATALEN (in I²S CFG1 register) greater than 23 (25-bit data or greater), the MSB of any received data will be forced to 0. If DATALEN = 24 (25-bit data), bit 24 of received data will always be 0. If DATALEN = 31 (32-bit data), bit 31 of received data will always be 0. The issue occurs regardless of the I²S operating mode (selected by MODE bits).

**Work-around:**

There is no work-around.
3.7 I²S.3: Incorrect synchronization to the second edge of the Word Select (WS) signal instead of the start of frame.

Introduction:

Multiple Flexcomm Interfaces are available in the LPC5411x devices. Flexcomm Interface 6 and Flexcomm Interface 7 can be configured for I²S peripheral function. The Word Select (WS) pin is the synchronizing signal for the beginning of each data frame and in some modes, left versus right channel data. It is normally driven by the master and received by one or more slaves.

Problem:

When I²S receives the WS signal from another master, that is, if MSTSLVCFG = 0x1 (WS Synchronized master) or 0x0 (Normal Slave mode) in the CFG1 register, and the I²S bus is already running, it can incorrectly synchronize to the second edge of the WS instead of the start of frame. This does not happen when the slave is started before the WS master.

Work-around:

The work-around is to detect the trailing edge on the WS pin and then enable the I²S interface. This can be achieved by using a rising or falling edge interrupt on a pin. The edge is determined by the starting mode of the WS pin. In I²S mode, the rising edge interrupt can be used so that the data frame starts from the falling edge. In DSP mode, the falling edge interrupt can be used so that the data frame starts from the rising edge.
3.8 I2C.1

Introduction:

In LPC5411x devices, the I2C interface has an AUTOACK bit in the Slave Control register. In the slave mode, when this bit is set, it will cause an I2C header, which matches the slave address SLVADR0 and the direction set by the AUTOMATCHREAD to be ACKed immediately. This is used with the DMA to allow processing of the data without intervention.

Problem:

The AUTOACK feature does not work reliably when the CPU system clock frequency is three times or more than the peripheral clock to the I2C interface.

Work-around:

The I2C peripheral clock frequency should be the same or half of the CPU system clock.
3.9 USART.1

**Introduction:**
A receiver timeout feature for the USART provides a means to get data left for a time in a FIFO that has not reached its threshold to be transferred. This feature exists in LPC5410x devices.

**Problem:**
The LPC5411x devices do not support the USART receiver timeout feature.

**Work-around:**
Timer0 can be used as a USART RX timeout timer and Flexcomm0 as USART0 peripheral in loop back mode. See the technical note TN00013 for more details.
3.10 USART.2

Introduction:
In the USART peripheral, the receiver idle (RXIDLE) interrupt occurs when the RX channel becomes idle. This feature exists in LPC5410x devices.

Problem:
The LPC5411x devices do not support the USART receiver idle (RXIDLE) interrupt feature.

Work-around:
There is no work-around.
3.11 CRP.1: Code read protection level 1 is not functional

**Introduction:**

Code Read Protection is a mechanism that allows the user to enable different levels of security in the system so that access to the on-chip flash and use of the ISP can be restricted. When needed, CRP is invoked by programming a specific pattern in the flash image at offset 0x0000 02FC. There are three levels of code read protection available to the user.

For CRP1 level, erase page command can erase pages in sector 0 only when all pages in the user flash are selected for erase.

**Problem:**

All pages in sector 0 except page 0 can be erased, which results in erasing CRP1 level.

**Work-around:**

Use CRP2 level or CRP3 level for code read protection.
3.12 USB_ROM.1: FRAME_INT is cleared if new SetConfiguration or USB_RESET are received.

**Introduction:**
In the USB ROM API, the function call EnableEvent can be used to enable and disable FRAME_INT.

**Problem:**
When the FRAME_INT is enabled through the USB ROM API call:

```
ErrorCode_t(* USBD_HW_API::EnableEvent)(USBD_HANDLE_T hUsb, uint32_t EPNum, uint32_t event_type, uint32_t enable),
```

the FRAME_INT is cleared if new SetConfiguration or USB_RESET are received.

**Work-around:**
Implement the following software work-around in the ISR to ensure that the FRAME_INT is enabled:

```c
void USB_IRQHandler(void)
{
    USBD_API->hw->EnableEvent(g_hUsb, 0, USB_EVT_SOF, 1);
    USBD_API->hw->ISR(g_hUsb);
}
```
3.13 USB_ROM.2: USB full-speed device fail in the Command/Data/Status Flow after bus reset and bus re-enumeration

Introduction:
The LPC5411x device family includes a USB full-speed interface that can operate in device mode and also, includes USB ROM based drivers. A Bulk-Only Protocol transaction begins with the host sending a CBW to the device and attempting to make the appropriate data transfer (In, Out or none). The device receives the CBW, checks and interprets it, attempts to satisfy the request of the host, and returns status via a CSW.

Problem:
When the device fails in the Command/Data/Status Flow, and the host does a bus reset / bus re-enumeration without issuing aBulk-Only Mass Storage Reset, the USB ROM driver does not re-initialize the MSC variables. This causes the device to fail in the Command/Data/Status Flow after the bus reset / bus re-enumeration.

Work-around:
Implement the following software work-around to re-initialize the MSC variables in the USBD stack.

```c
void *g_pMscCtrl;
ErrorCode_t mwMSC_Reset_workaround(USBD_HANDLE_T hUsb)
{
(USB_MSC_CTRL_T *)g_pMscCtrl)->CSW.dSignature = 0;
(USB_MSC_CTRL_T *)g_pMscCtrl)->BulkStage = 0;
return LPC_OK;
}

ErrorCode_t mscDisk_init(USBD_HANDLE_T hUsb, USB_CORE_DESCS_T *pDesc,
USBD_API_INIT_PARAM_T *pUsbParam)
{
USBD_MSC_INIT_PARAM_T msc_param;
ErrorCode_t ret = LPC_OK;
memset((void *)&msc_param, 0, sizeof(USBD_MSC_INIT_PARAM_T));
msc_param.mem_base = pUsbParam->mem_base;
msc_param.mem_size = pUsbParam->mem_size;
g_pMscCtrl = (void *)msc_param.mem_base;
ret = USBD_API->msc->init(hUsb, &msc_param);
/* update memory variables */
pUsbParam->mem_base = msc_param.mem_base;
pUsbParam->mem_size = msc_param.mem_size;
```

return ret;
}

usb_param.USB_Reset_Event = mwMSC_Reset_workaround;
ret = USBD_API->hw->Init(&g_hUsb, &desc, &usb_param);
4. AC/DC deviations detail

4.1 \( V_{\text{REFP}} < V_{\text{DD}} \): For \( V_{\text{REFP}} < V_{\text{DD}} \), the deep power-down current is higher than expected.

Introduction:
When \( V_{\text{DDA}} \geq 2 \text{ V} \), the ADC positive reference voltage \( (V_{\text{refp}}) \) has a specification of 2.0 V minimum and \( V_{\text{DDA}} \) maximum voltage. When \( V_{\text{DDA}} < 2 \text{ V} \), the ADC positive reference voltage \( (V_{\text{refp}}) \) must be equal to \( V_{\text{DDA}} \). Also, the supply voltage \( V_{\text{DD}} \) must be equal to \( V_{\text{DDA}} \).

Problem:
For \( V_{\text{DDA}} \geq 2 \text{ V} \) and \( V_{\text{refp}} < V_{\text{DDA}} \), the \( V_{\text{DD}} \) current consumption in deep power-down mode can be higher than the specified data sheet value. This issue does not occur for other low power modes, and also, when \( V_{\text{refp}} \) is equal to \( V_{\text{DDA}} \).

Work-around:
There is no work-around.
5. **Errata notes**

No known errata.
6. Legal information

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